Lead free, No-clean solder wire

Description:

Interflux® **IF R88** Lead-Free, No-clean solder wire is a mildly activated rosin based wire recommended when soldering in **classes I, II** (IPC-A-610).

It is especially well suited for surfaces with poor wettability and those applications where good solderability, fast wetting and excellent solder spreading are needed.

IF R88 has increased activity and shows very good through hole wetting and soldering speed even with SnCu lead–free alloys.

IF **R88** shows excellent results in automated and robotic soldering.

More information:

Key advantages:

- Classification to IPC and EN: **ROL1**
- Mildly activated
- For automated soldering
- Excellent wetting on surfaces with poor wettability

Availability

Flux type: **R88**
Flux content: 2,2% - 3,5% w/w

alloy	melting point	diameters 0,20	0,35	0,50	0,70	1,00	1,50	2,00
Sn96,5Ag3Cu0,5	217°C—219°C	●	●	●	●	●	●	●
Sn96,5Ag3,5	221°C	●	●	●	●	●	●	●
Sn95,5Ag3,8Cu0,7	217°C-219°C	●	●	●	●	●	●	●
Sn99Ag0,3Cu0,7	217°C-227°C	●	●	●	●	●	●	●
Sn99,3Cu0,7	227°C	●	●	●	●	●	●	●

● = available ● = upon request

Work instructions

Manual soldering

The working temperature is between 360°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component and solder pad.

The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible.

Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire, the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. It is important that no solder wire is making contact with the soldering tip during soldering to avoid flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care

Test results

Conform EN 61190-1-3(2007), IPC J-STD-004 and Bellcore

Property	Result	Method
Chemical		
flux designator	**ROL1**	J-STD-004
	F-SW 26	DIN 8511
	1.1.2	ISO 9454
qualitative copper mirror	**pass**	J-STD-004 IPC-TM-650 2.3.32
	pass	GR-78-CORE Rev. 9/97 13.1.6
qualitative halide		
silver chromate (Cl, Br)	**pass**	J-STD-004 IPC-TM-650 2.3.33
	pass	GR-78-CORE Rev. 9/97 13.1.4
spot test (F)	**pass**	J-STD-004 IPC-TM-650 2.3.35.1
Environmental		
SIR test	**pass**	J-STD-004 IPC-TM-650 2.6.3.3
	pass	GR-78-CORE Rev. 9/97 13.1.4
qualitative corrosion, flux	**pass**	J-STD-004 IPC-TM-650 2.6.15
electro chemical migration	**pass**	GR-78-CORE Rev. 9/97 13.1.5

Packaging

Spools of 100g, 500g and 1000g

D i s c l a i m e r

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